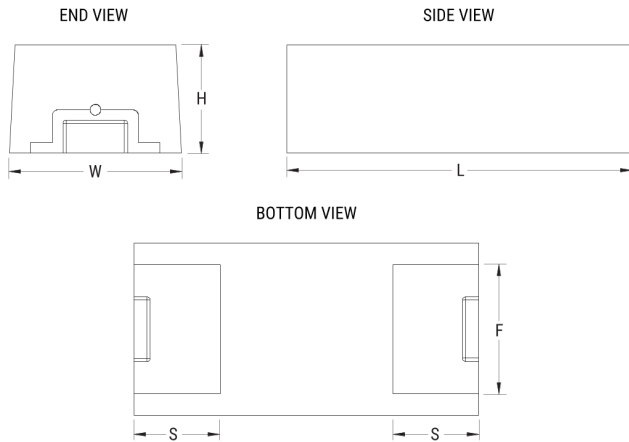


TEFPSA30G107M8R

Aliases (FPSA30G107M8R-T&R)

F/PS, Tantalum, Polymer Tantalum, Reduced Volume, 100 uF, 20%, 4 VDC, SMD, Polymer, Molded, Low ESR, Face Down Terminals, 200 mOhms, 3216, Height Max = 1mm



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|----------------|
| Footprint | 3216 |
| L | 3.2mm +/-0.2mm |
| W | 1.6mm +/-0.2mm |
| H | 0.9mm +/-0.1mm |
| S | 0.7mm +/-0.2mm |
| F | 1.2mm +/-0.1mm |

Packaging Specifications

Packaging T&R, 178mm

General Information

| | |
|-------------|--|
| Series | F/PS |
| Dielectric | Polymer Tantalum |
| Style | SMD Chip |
| Description | SMD, Polymer, Molded, Low ESR, Face Down Terminals |
| Features | Low ESR, Face Down Terminal |
| RoHS | Yes |
| Termination | Tin |
| AEC-Q200 | No |

Specifications

| | |
|-----------------------|--------------------------------|
| Capacitance | 100 uF |
| Capacitance Tolerance | 20% |
| Voltage DC | 4 VDC (105°C), 5.2 VDC (Surge) |
| Temperature Range | -55/+105°C |
| Rated Temperature | 105°C |
| Dissipation Factor | 8% |
| Failure Rate | N/A |
| Resistance | 0.2 Ohms (100kHz) |
| Ripple Current | 548 mAmps (25C) |
| Leakage Current | 40 uA |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)